



Docket: CS 99 - 065CC
/N: 09/442,499

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1763.

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To: Commissioner for Patents
P.O. Box 1450
Alexandria, Virginia 22313-1450

From: George O. Saile, Reg. No. 19,572
28 Davis Avenue
Poughkeepsie, N.Y. 12603

Subject:

Serial No.: 09/442,499	Filed: 11/18/1999
Inventor: Ho	
Title: Plasma Etch Method For Forming Plasma Etched Silicon Layer	
Group Art Unit: 1763	Examiner: Goudreau, G. A.
Attorney Docket: CS 99 - 065CC	

RESPONSE TO PATENT OFFICE ACTION

Dear Sir:

In response to the office action dated 10/23/2003, please consider the following remarks:

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, Virginia 22313-1450, on January 23, 2004.

Signature/Date

1/23/04

Stephen B. Ackerman
Reg. No. 37,761